



AF/2828

[2345/119]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Hartwig RICHTER et al.  
Serial No. : 09/529,700  
Filed : April 18, 2000  
Title : SEMICONDUCTOR LASER CHIP  
Art Unit : 2828  
Examiner : James Davie

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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Date: June 24, 2003

Signature:   
Linda M. Shudy (Reg. no. 47,084)

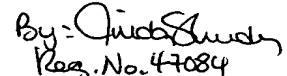
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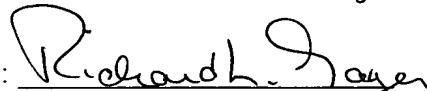
TRANSMITTAL OF AMENDMENT

SIR:

Transmitted herewith for filing in the above-identified patent application is an Amendment in response to an Office Action made Final dated June 2, 2003.

No fee is believed due at this time. However, the Commissioner is authorized, as appropriate and/or necessary, to charge any additional fees (including any Rule 136(a) extension fees) or credit any overpayment to Deposit Account No. 11-0600. A duplicate copy of this transmittal letter is enclosed for that purpose.

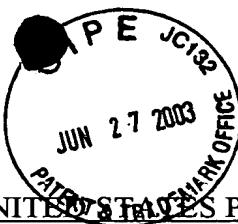
Respectfully submitted, By:   
Linda M. Shudy (Reg. no. 47,084)

By:   
Richard L. Mayer  
(Reg. No. 22,490)

Dated: June 24, 2003

CUSTOMER NO. 26646

KENYON & KENYON  
One Broadway  
New York, New York 10004  
(212) 425-7200

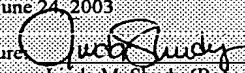


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Linda M. Shudy (Reg. no. 47,084)

AMENDMENT

Sir:

In response to the Office Action dated June 2, 2003, please reconsider the above-identified application based on the following:

Approved for entry  
J. D.  
7/4/03  
D.  
D<sup>2</sup>  
D<sup>3</sup>

IN THE CLAIMS:

Please amend claims 35, 38, 41 and 45 as follows:

35. (Amended) The semiconductor laser as recited in claim 34 wherein prior to the welding each of the at least one temperature sensor is sealed into an electrically insulating glass.

D<sup>2</sup>  
D<sup>3</sup>

38. (Amended) The semiconductor laser as recited in claim 37 wherein the wires for measuring the electrical resistance through the semiconductor laser chip include a pumping current lead wire and an additional wire used as a sensor supply lead.

41. (Amended) The semiconductor laser as recited in claim 40 wherein a contact surface of a material of one of the wires is deposited on the semiconductor laser chip before the two wires are joined.

ENTERED  
7/16/03  
D.King